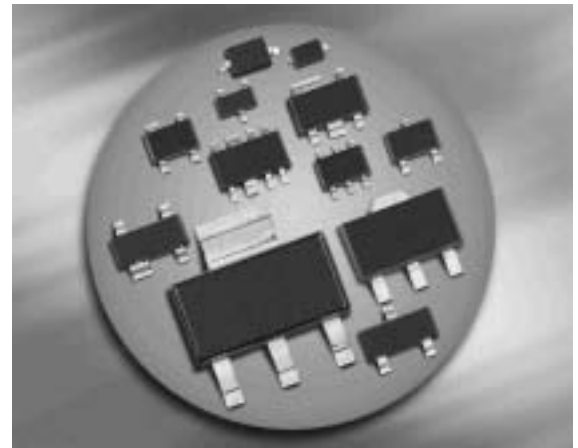
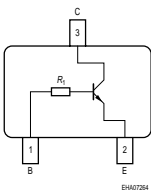
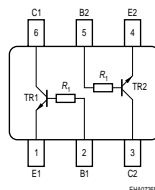


NPN Silicon Digital Transistor

- Switching circuit, inverter, interface circuit, driver circuit
- Built in bias resistor ($R_1=10\text{ k}\Omega$)
- BCR129S: Two internally isolated transistors with good matching in one multichip package
- BCR129S: For orientation in reel see package information below
- Pb-free (RoHS compliant) package ¹⁾
- Qualified according AEC Q101


**BCR129/F
BCR129W**

BCR129S


Type	Marking	Pin Configuration						Package
		1=B	2=E	3=C	-	-	-	
BCR129	WVs	1=B	2=E	3=C	-	-	-	SOT23
BCR129F	WVs	1=B	2=E	3=C	-	-	-	TSFP-3
BCR129S	WVs	1=E1	2=B1	3=C2	4=E2	5=B2	6=C1	SOT363
BCR129W	WVs	1=B	2=E	3=C	-	-	-	SOT323

¹Pb-containing package may be available upon special request

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CEO}	50	V
Collector-base voltage	V_{CBO}	50	
Input forward voltage	$V_{i(fwd)}$	40	
Input reverse voltage	$V_{i(rev)}$	5	
Collector current	I_C	100	mA
Total power dissipation- BCR129, $T_S \leq 102^\circ\text{C}$ BCR129F, $T_S \leq 128^\circ\text{C}$ BCR129S, $T_S \leq 115^\circ\text{C}$ BCR129W, $T_S \leq 124^\circ\text{C}$	P_{tot}	200 250 250 250	mW
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-65 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾ BCR129 BCR129F BCR129S BCR129W	R_{thJS}	≤ 240 ≤ 90 ≤ 140 ≤ 105	K/W

¹For calculation of R_{thJA} please refer to Application Note Thermal Resistance

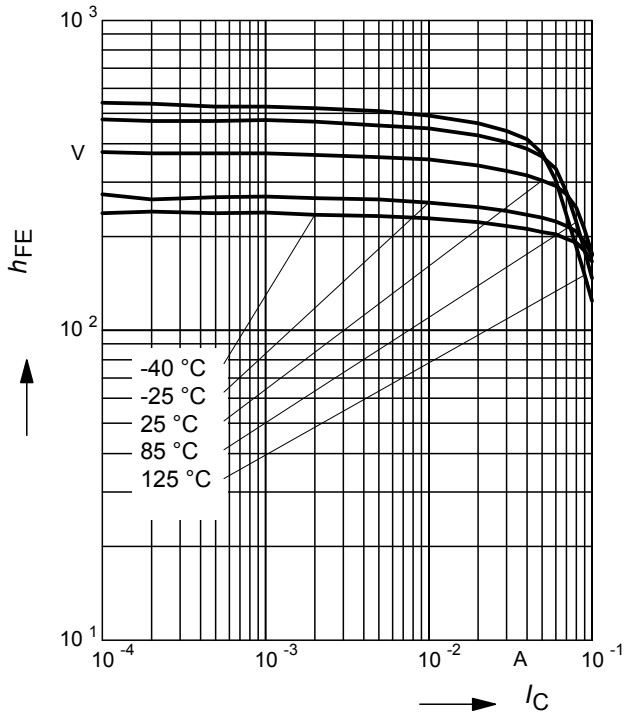
Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage $I_C = 100 \mu\text{A}, I_B = 0$	$V_{(BR)CEO}$	50	-	-	V
Collector-base breakdown voltage $I_C = 10 \mu\text{A}, I_E = 0$	$V_{(BR)CBO}$	50	-	-	
Collector-base cutoff current $V_{CB} = 40 \text{ V}, I_E = 0$	I_{CBO}	-	-	100	nA
Emitter-base cutoff current $V_{EB} = 5 \text{ V}, I_C = 0$	I_{EBO}	-	-	100	nA
DC current gain ¹⁾ $I_C = 5 \text{ mA}, V_{CE} = 5 \text{ V}$	h_{FE}	120	-	630	-
Collector-emitter saturation voltage ¹⁾ $I_C = 10 \text{ mA}, I_B = 0.5 \text{ mA}$	V_{CEsat}	-	-	0.3	V
Input off voltage $I_C = 100 \mu\text{A}, V_{CE} = 5 \text{ V}$	$V_{i(off)}$	0.4	-	1	
Input on voltage $I_C = 2 \text{ mA}, V_{CE} = 0.3 \text{ V}$	$V_{i(on)}$	0.5	-	1.1	
Input resistor	R_1	7	10	13	k Ω
AC Characteristics					
Transition frequency $I_C = 10 \text{ mA}, V_{CE} = 5 \text{ V}, f = 100 \text{ MHz}$	f_T	-	150	-	MHz
Collector-base capacitance $V_{CB} = 10 \text{ V}, f = 1 \text{ MHz}$	C_{cb}	-	3	-	pF

¹⁾Pulse test: $t < 300 \mu\text{s}$; $D < 2\%$

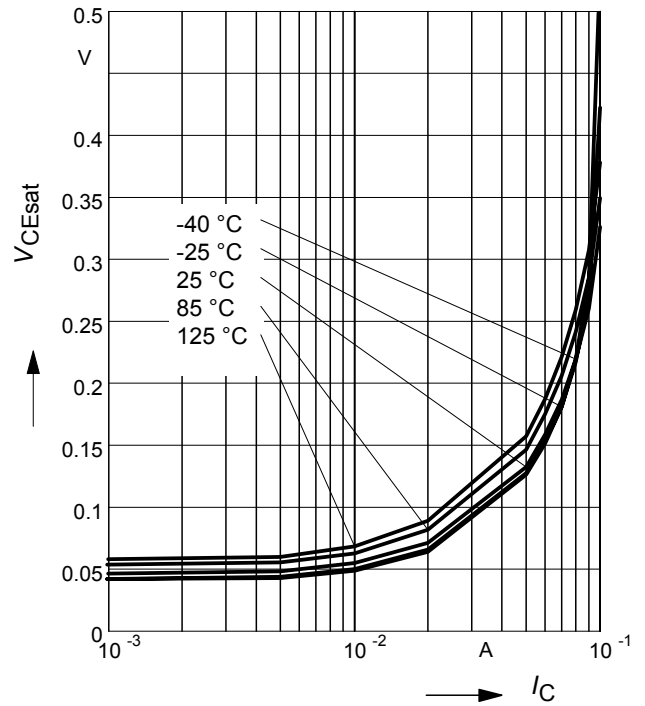
DC current gain $h_{FE} = f(I_C)$

$V_{CE} = 5\text{ V}$ (common emitter configuration)



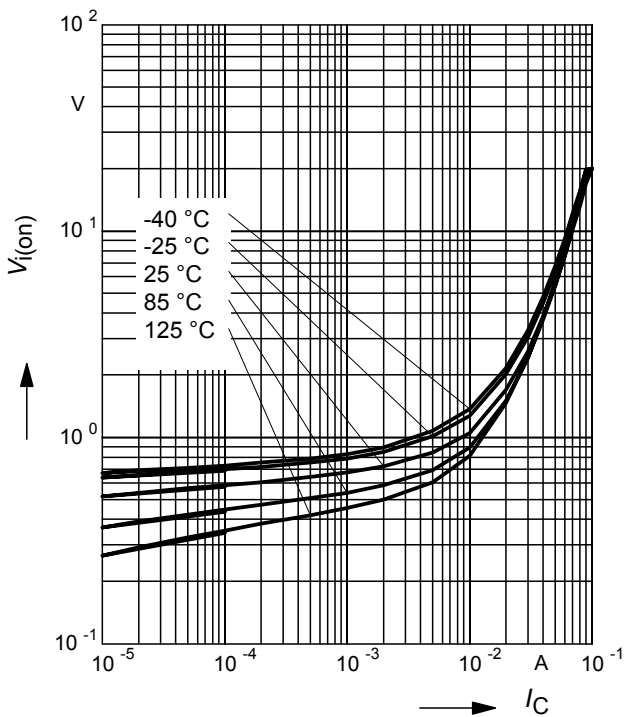
Collector-emitter saturation voltage

$V_{CEsat} = f(I_C), I_C/I_B = 20$



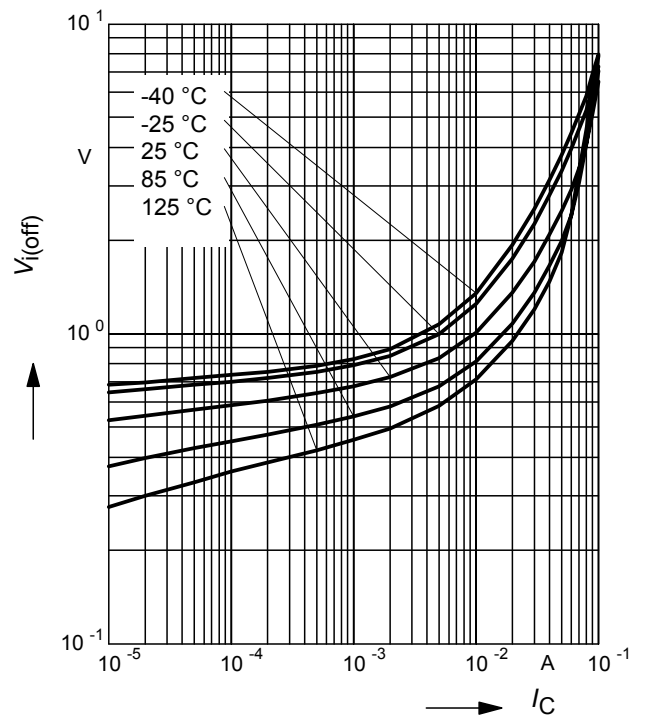
Input on Voltage $V_{i(on)} = f(I_C)$

$V_{CE} = 0.3\text{ V}$ (common emitter configuration)

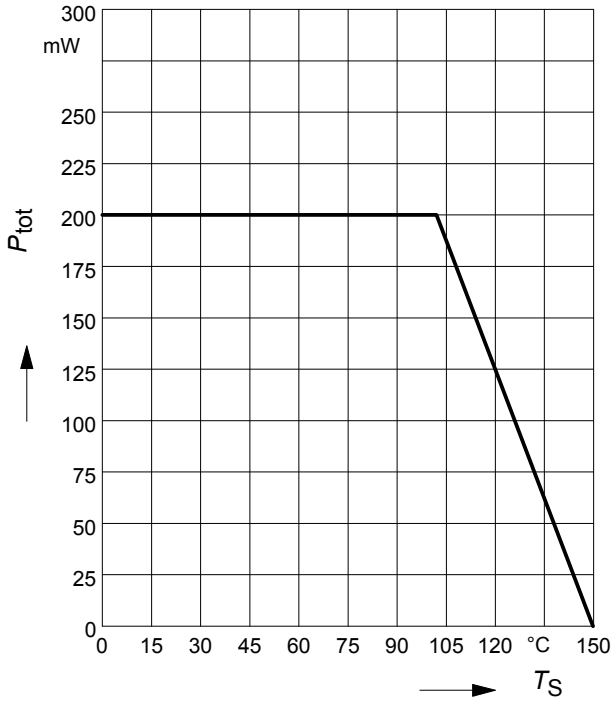


Input off voltage $V_{i(off)} = f(I_C)$

$V_{CE} = 5\text{ V}$ (common emitter configuration)

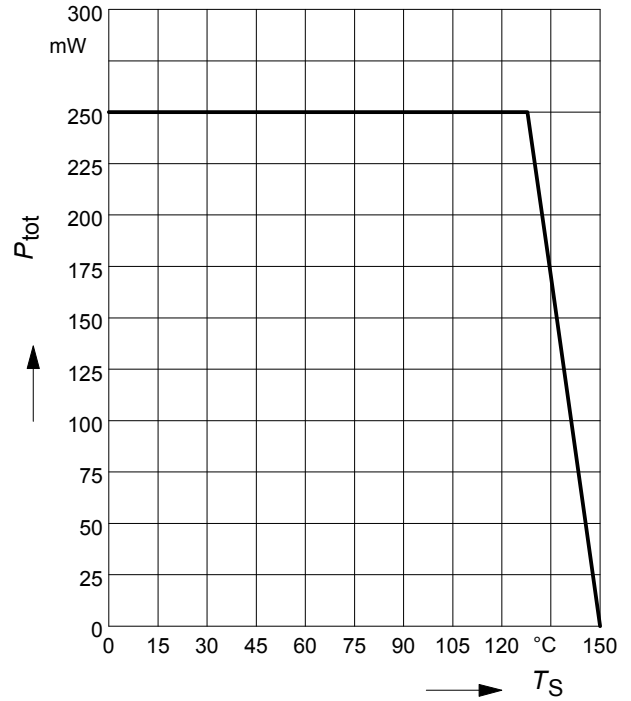


Total power dissipation $P_{tot} = f(T_S)$



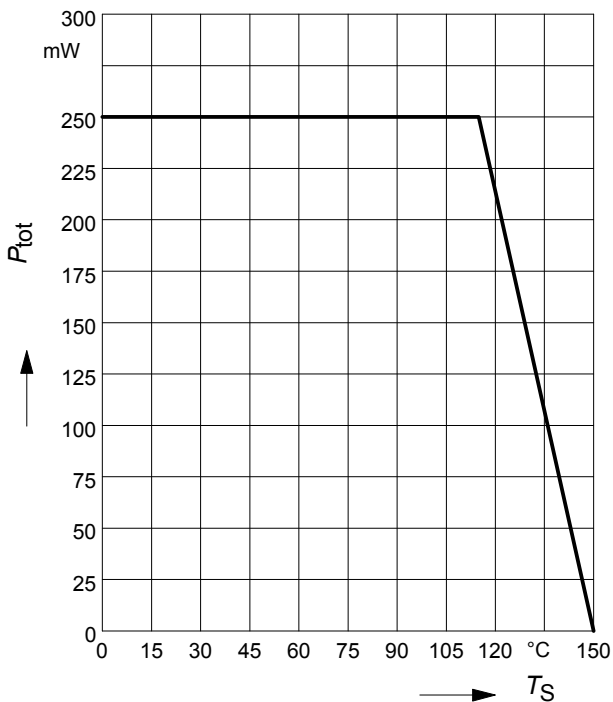
Total power dissipation $P_{tot} = f(T_S)$

BCR129F



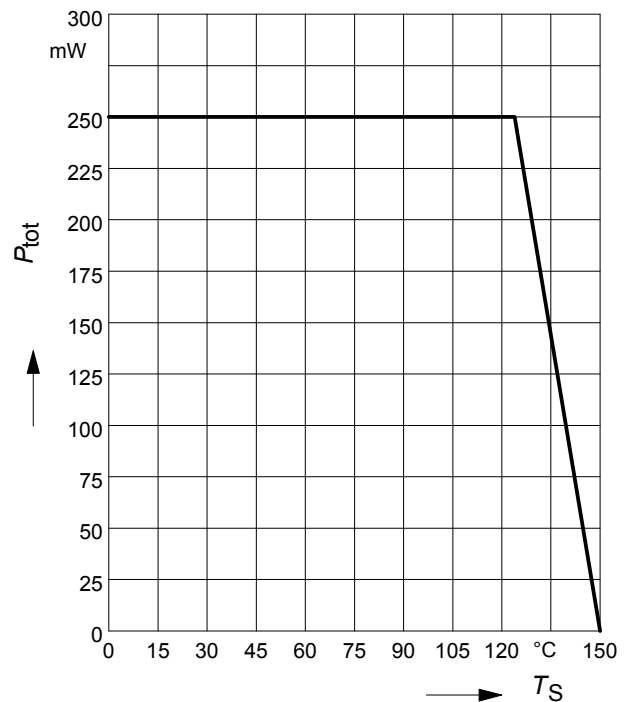
Total power dissipation $P_{tot} = f(T_S)$

BCR129S



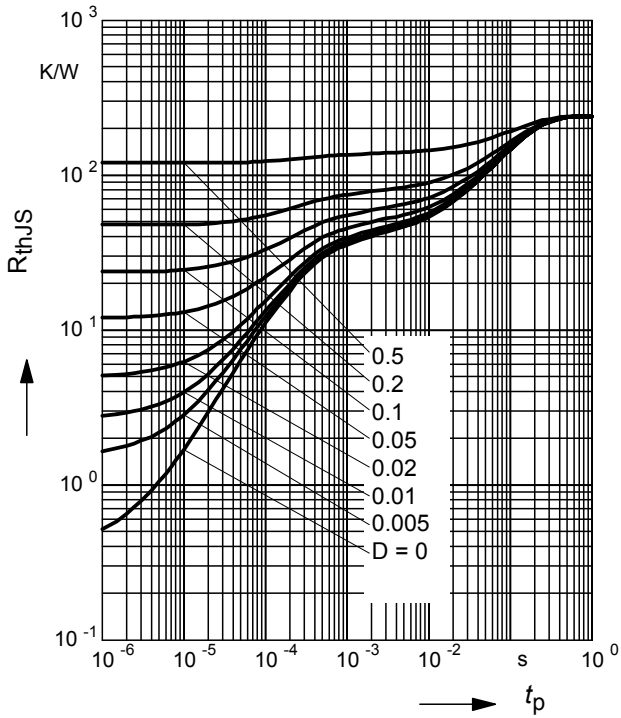
Total power dissipation $P_{tot} = f(T_S)$

BCR129W



Permissible Pulse Load $R_{thJS} = f(t_p)$

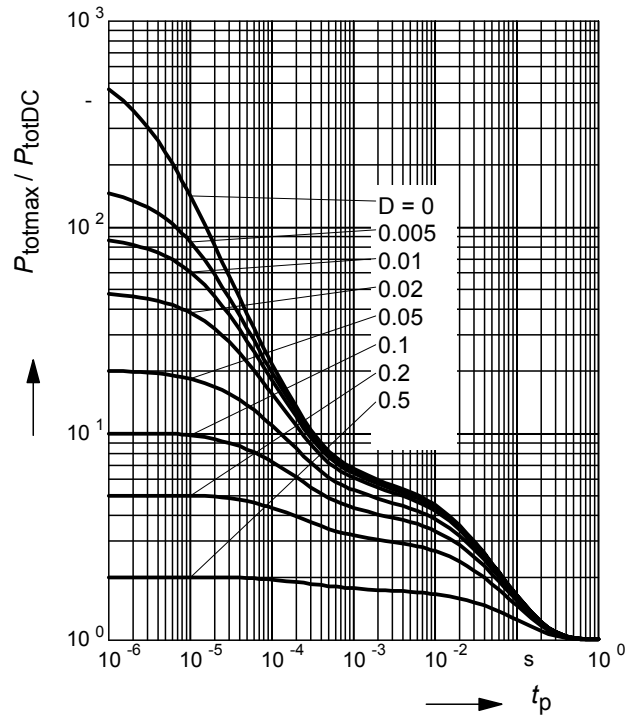
BCR129



Permissible Pulse Load

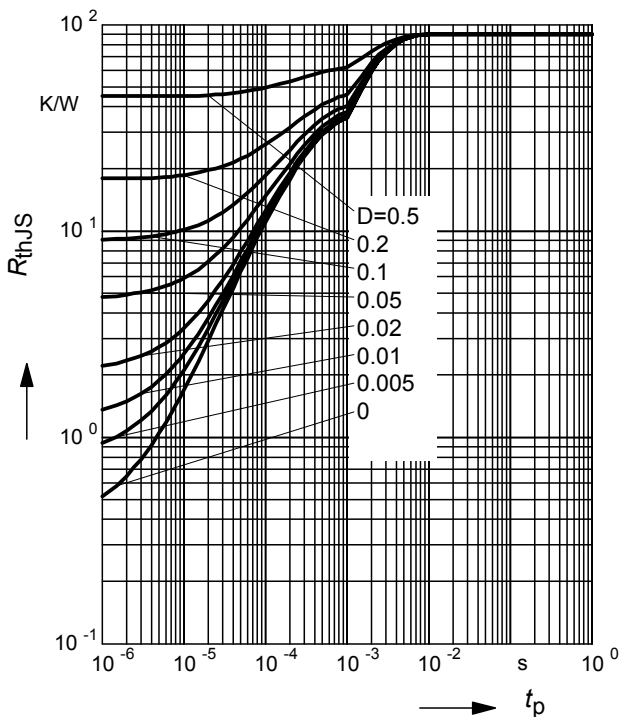
$P_{totmax}/P_{totDC} = f(t_p)$

BCR129



Permissible Puls Load $R_{thJS} = f(t_p)$

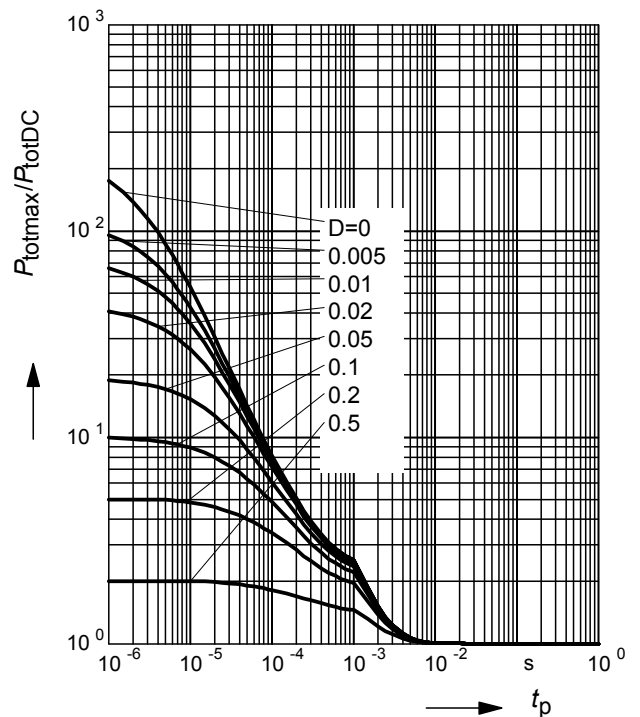
BCR129F



Permissible Pulse Load

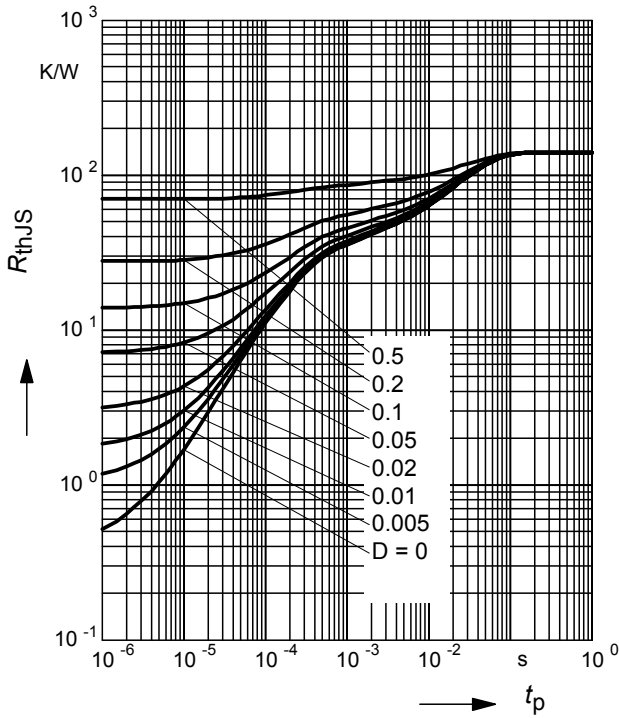
$P_{totmax}/P_{totDC} = f(t_p)$

BCR129F



Permissible Puls Load $R_{thJS} = f(t_p)$

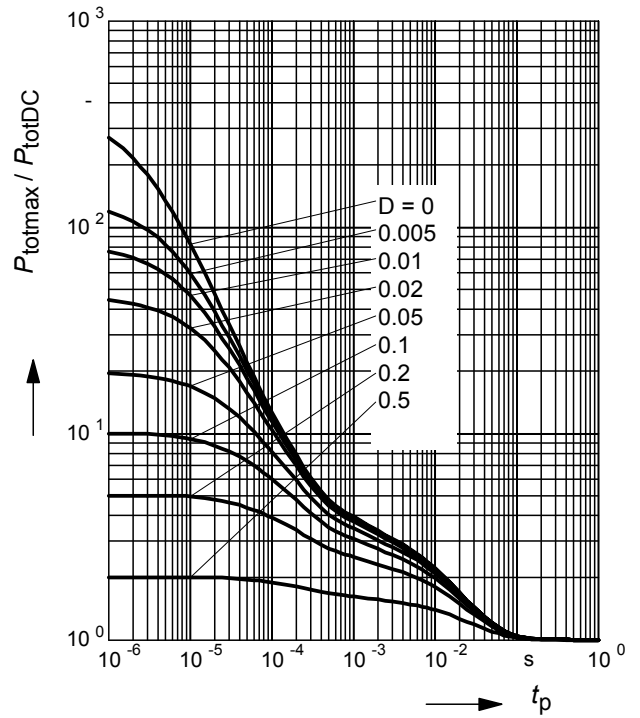
BCR129S



Permissible Pulse Load

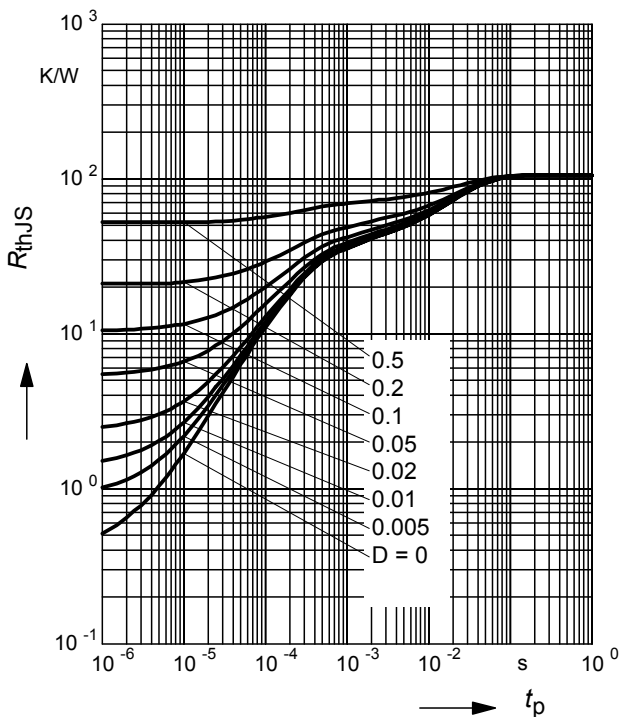
$P_{totmax}/P_{totDC} = f(t_p)$

BCR129S



Permissible Puls Load $R_{thJS} = f(t_p)$

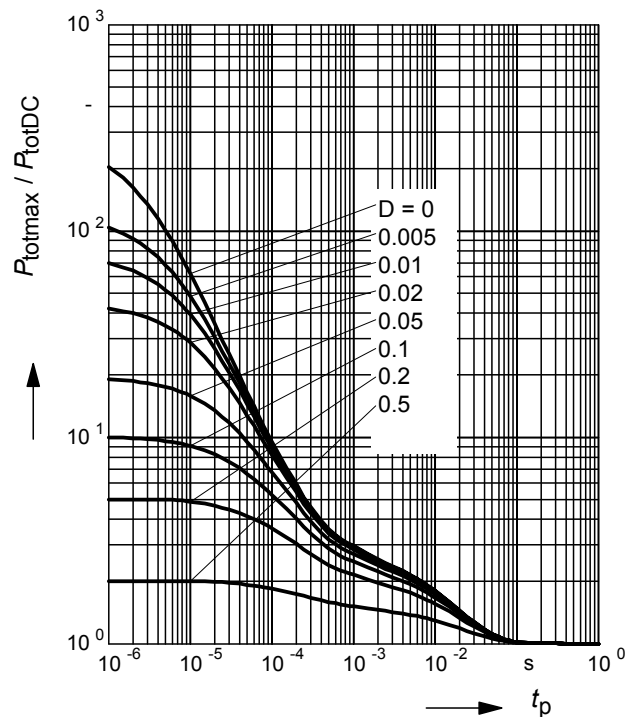
BCR129W



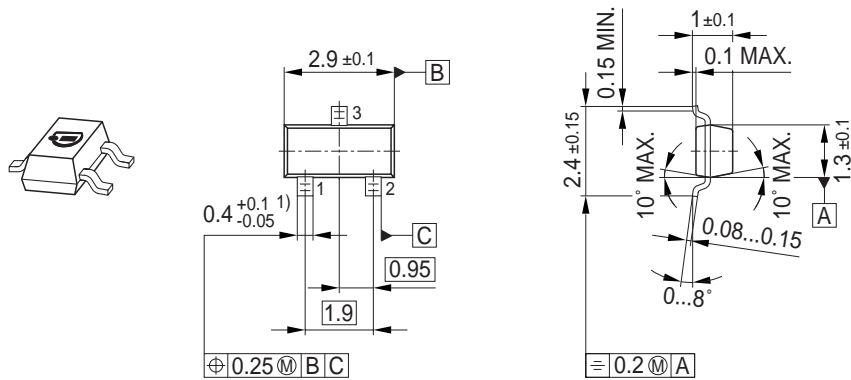
Permissible Pulse Load

$P_{totmax}/P_{totDC} = f(t_p)$

BCR129W

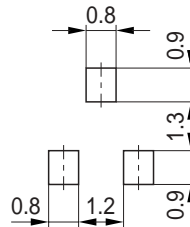


Package Outline

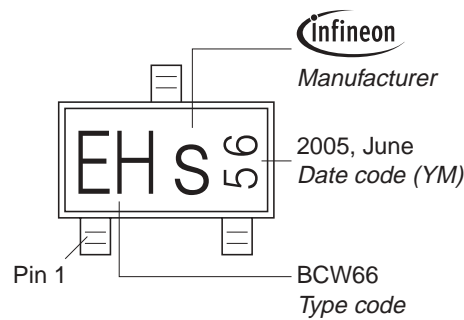


1) Lead width can be 0.6 max. in dambar area

Foot Print

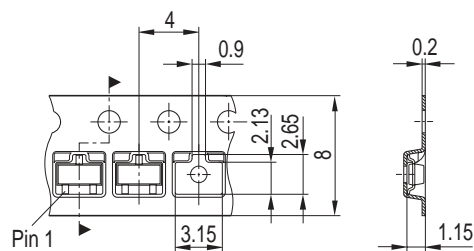


Marking Layout (Example)

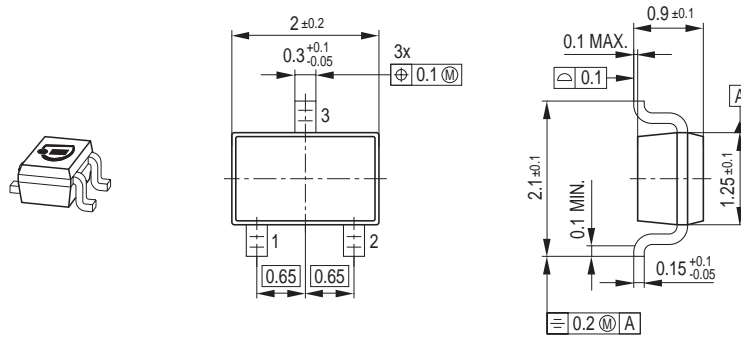


Standard Packing

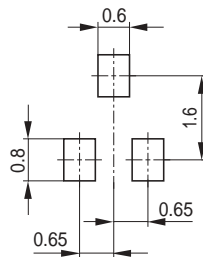
Reel \varnothing 180 mm = 3.000 Pieces/Reel
 Reel \varnothing 330 mm = 10.000 Pieces/Reel



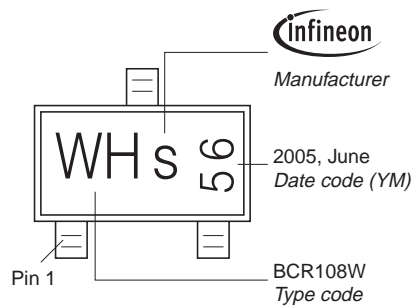
Package Outline



Foot Print

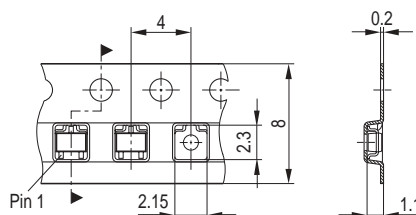


Marking Layout (Example)

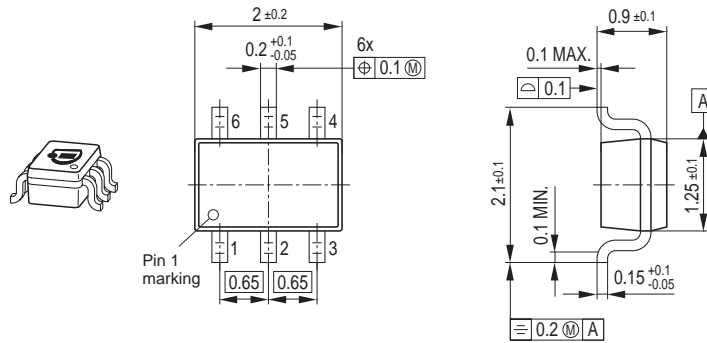


Standard Packing

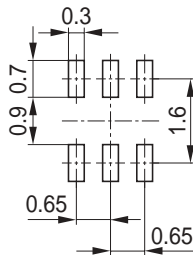
Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel



Package Outline

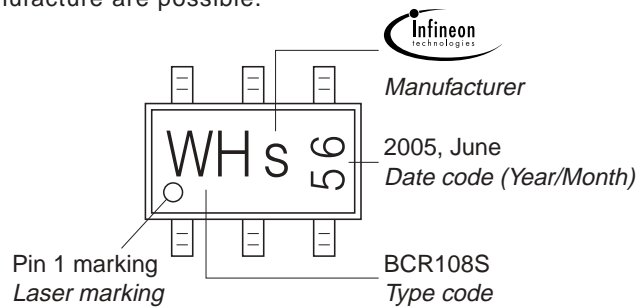


Foot Print



Marking Layout (Example)

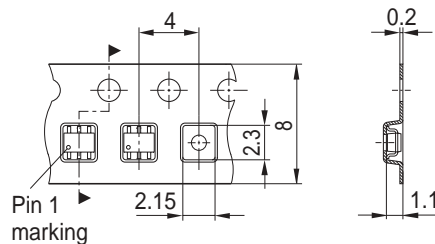
Small variations in positioning of Date code, Type code and Manufacture are possible.



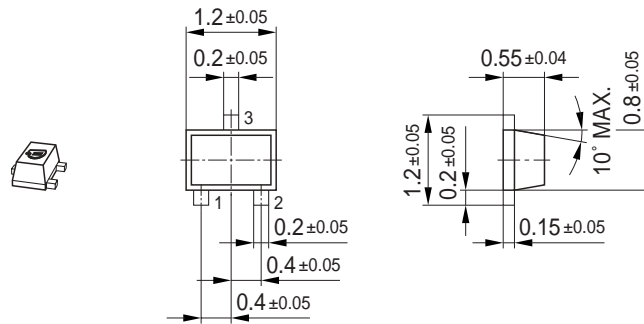
Standard Packing

Reel \varnothing 180 mm = 3.000 Pieces/Reel
 Reel \varnothing 330 mm = 10.000 Pieces/Reel

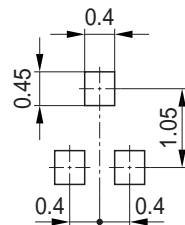
For symmetric types no defined Pin 1 orientation in reel.



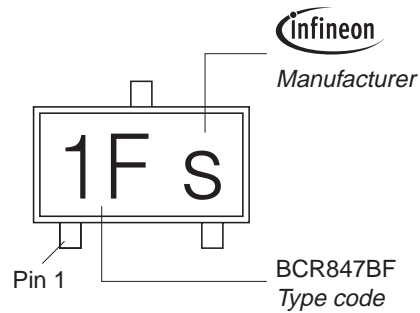
Package Outline



Foot Print

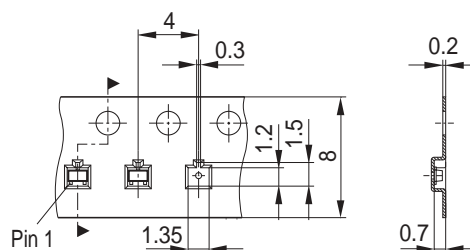


Marking Layout (Example)



Standard Packing

Reel \varnothing 180 mm = 3.000 Pieces/Reel
 Reel \varnothing 330 mm = 10.000 Pieces/Reel



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